

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	ASSIGNMENT
RESUBMIT DOCUMENT ID:	507911499
CONVEYING PARTY DATA	
Name	Execution Date
BYUNG WOO KANG	03/29/2021
BON SEOK KOO	03/29/2021
JEONG RYEOL KIM	03/29/2021
JUNG MIN KIM	03/29/2021
JAE SEOK YI	03/29/2021
JI HYE HAN	03/29/2021
HYE JIN PARK	03/29/2021
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
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City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18198419
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DATE SIGNED:	07/26/2023

PATENT

Total Attachments: 3

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Title of
Invention

MULTILAYER ELECTRONIC COMPONENT

DECLARATION

This declaration
is directed to:

X

The attached application, or



United States application or PCT international application number
filed on

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: *A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56.*

ASSIGNMENT

WHEREAS, I have made an invention described and/or claimed in the above-identified application; and

WHEREAS, SAMSUNG ELECTRO-MECHANICS CO., LTD., a corporation of the Republic of Korea, having a place of business at Macyoung-Ro 150 (Maetan-Dong), Youngtong-Gu, Suwon-Si, Gyeonggi-Do, Republic of Korea, (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title, and interest in and to said invention in all countries throughout the world and the above-identified United States patent application;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have assigned and do hereby assign to the ASSIGNEE, and its lawful successors and assigns, the entire right, title, and interest in and to said invention, the above-identified United States patent application and all divisions, continuations, and continuations-in-part of said application, and reissues, extensions, and renewals of Letters Patent granted thereon, and all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and all Letters Patents issuing on any such patent applications in the United States and foreign countries;

I hereby assign to the ASSIGNEE, and its lawful successors and assigns, the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any

other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Byung Woo KANG

Signature: _____



Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Bon Seok KOO

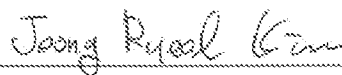
Signature: _____



Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Jeong Ryeol KIM

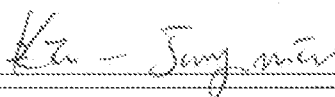
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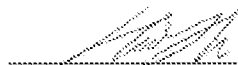
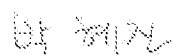
Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Jung Min KIM

Signature: _____



Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : <u>Jae Seok YI</u>	
Signature: <u></u>	Date: <u>2021.03.29</u>
NAME OF INVENTOR (Full Legal Name) : <u>Ji Hye HAN</u>	
Signature: <u></u>	Date: <u>2021.03.29</u>
NAME OF INVENTOR (Full Legal Name) : <u>Hye Jin PARK</u>	
Signature: <u></u>	Date: <u>2021.03.29</u>